



# N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI5060-8

### **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>C</sub> = +25°C
201/	5.5mΩ @ V <sub>GS</sub> = 10V	71.1A
30V	9.6mΩ @ V <sub>GS</sub> = 4.5V	53.8A

#### **Features and Benefits**

- Low Rds(ON) Minimizes On-State Losses
- Excellent Q<sub>gd</sub> x R<sub>DS(ON)</sub> Product (FOM)
- Advanced Technology for DC-DC Converters
- Small Form Factor Thermally Efficient Package Enables Higher Density End Products
- 100% Unclamped Inductive Switching Ensures More Reliability
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative.

https://www.diodes.com/quality/product-definitions/

### **Description and Applications**

This MOSFET is designed to minimize the on-state resistance (R<sub>DS(ON)</sub>) yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

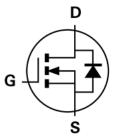
- Backlighting
- Power-management functions
- DC-DC converters

#### **Mechanical Data**

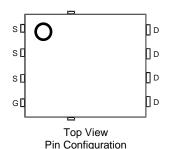
- Package: PowerDI<sup>®</sup>5060-8
- Package Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
   Solderable per MIL-STD-202, Method 208
- Weight: 0.097 grams (Approximate)







Internal Schematic



#### Ordering Information (Note 4)

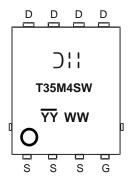
Part Number	Paskage	Packing		
Fait Number	Package	Qty.	Carrier	
DMT35M4LPSW-13	PowerDI5060-8/SWP (Type UX)	2,500	Tape & Reel	

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



### **Marking Information**



Dil = Manufacturer's Marking T35M4SW = Product Type Marking Code YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 23 = 2023)
WW = Week Code (01 to 53)

## Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	VDSS	30	V	
Gate-Source Voltage	Vgss	±20	V	
Continuous Drain Current, V <sub>GS</sub> = 10V (Note 5)	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	lD	18.9 15.1	А
Continuous Drain Current, V <sub>GS</sub> = 10V (Note 6) $ T_C = +25^{\circ}C $ $ T_C = +70^{\circ}C $		lD	71.1 56.9	А
Maximum Continuous Body Diode Forward Current (Note 5)	Is	3	Α	
Pulsed Drain Current (380µs Pulse, Duty Cycle = 1%)	Ідм	288	Α	
Pulsed Body Diode Forward Current (380µs Pulse, Duty Cycle	lsм	288	Α	
Avalanche Current, L = 0.1mH (Note 7)	las	24.9	А	
Avalanche Energy, L = 0.1mH (Note 7)	Eas	31	mJ	

### **Thermal Characteristics**

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 8)	T <sub>A</sub> = +25°C	PD	1.5	W
Thermal Resistance, Junction to Ambient (Note 8)  Steady State		$R_{\theta JA}$	83.5	°C/W
Total Power Dissipation (Note 5) T <sub>A</sub> = +25°C		P <sub>D</sub>	2.9	W
Thermal Resistance, Junction to Ambient (Note 5)  Steady State		Reja	42.5	°C/W
Thermal Resistance, Junction to Case (Note 6)	Rejc	3	°C/W	
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C	

 5. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
 6. Thermal resistance from junction to soldering point (on the exposed drain pad).
 7. I<sub>s</sub> and E<sub>AS</sub> ratings are based on low frequency and duty cycles to keep T<sub>J</sub> = +25°C. Notes:

<sup>8.</sup> Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.



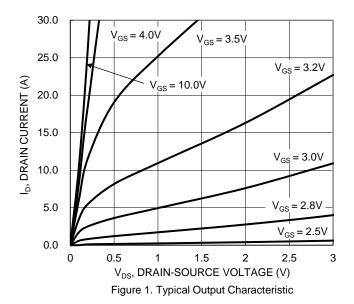
### **Electrical Characteristics** (T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	30	_	_	V	$V_{GS} = 0V, I_{D} = 250\mu A$	
Zero Gate Voltage Drain Current	IDSS	_	_	1	μA	V <sub>DS</sub> = 24V, V <sub>GS</sub> = 0V	
Gate-Source Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)							
Gate Threshold Voltage	VGS(TH)	1	_	2.5	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
Static Drain-Source On-Resistance	D	_	4.6	5.5	mΩ	$V_{GS} = 10V, I_D = 20A$	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	_	7.1	9.6	11177	$V_{GS} = 4.5V, I_D = 20A$	
Diode Forward Voltage	VsD	_	0.7	1.2	V	V <sub>G</sub> S = 0V, I <sub>S</sub> = 2A	
DYNAMIC CHARACTERISTICS (Note 10)							
Input Capacitance	Ciss	_	1029	_		V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V f = 1.0MHz	
Output Capacitance	Coss	_	910	_	pF		
Reverse Transfer Capacitance	Crss	_	58	_			
Gate Resistance	Rg	_	1.9	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ f = 1.0MHz	
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	_	16	_		V <sub>DD</sub> = 15V, I <sub>D</sub> = 20A	
Total Gate Charge (VGS = 4.5V)	Qg	_	7.9	_	nC		
Gate-Source Charge	Qgs	_	3.3	_	IIC		
Gate-Drain Charge	$Q_{gd}$	_	2.3	_			
Turn-On Delay Time	td(on)	_	3.2	_		$V_{DD}=15V,V_{GS}=10V$ $R_g=3\Omega,I_D=20A$	
Turn-On Rise Time	t <sub>R</sub>	_	3.4	_			
Turn-Off Delay Time	tD(OFF)	_	17	_	ns		
Turn-Off Fall Time	tF	_	5.5	_			

Notes:

<sup>9.</sup> Short duration pulse test used to minimize self-heating effect. 10. Guaranteed by design. Not subject to product testing.





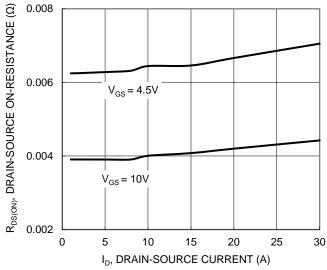


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

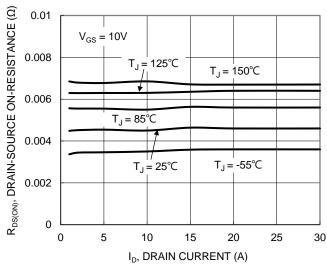


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

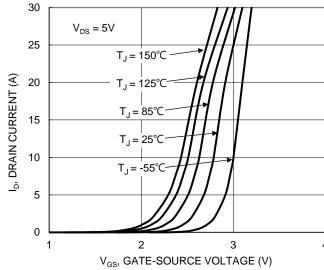


Figure 2. Typical Transfer Characteristic

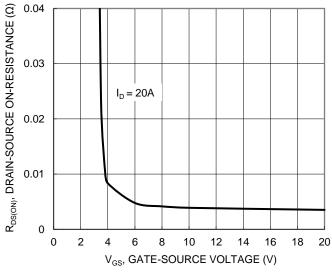


Figure 4. Typical Transfer Characteristic

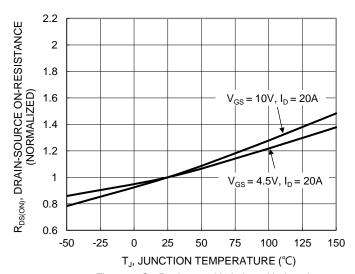


Figure 6. On-Resistance Variation with Junction Temperature



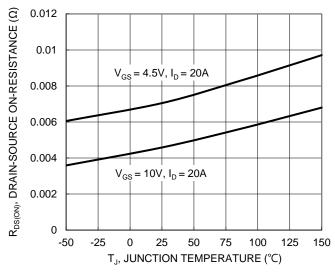


Figure 7. On-Resistance Variation with Junction Temperature

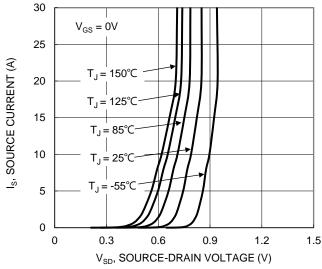


Figure 9. Diode Forward Voltage vs. Current

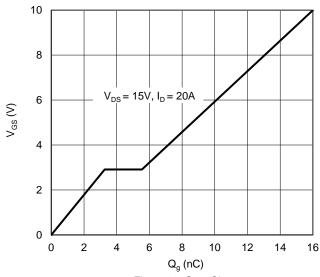


Figure 11. Gate Charge

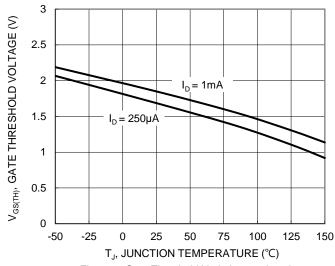


Figure 8. Gate Threshold Variation vs. Junction Temperature

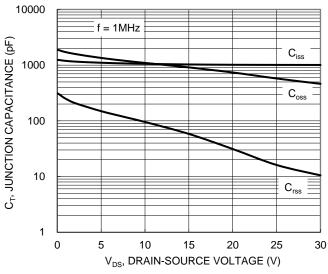


Figure 10. Typical Junction Capacitance

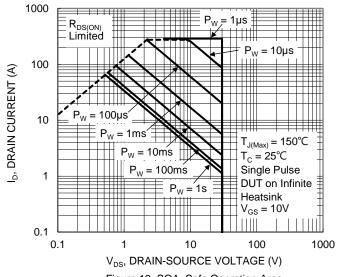


Figure 12. SOA, Safe Operation Area



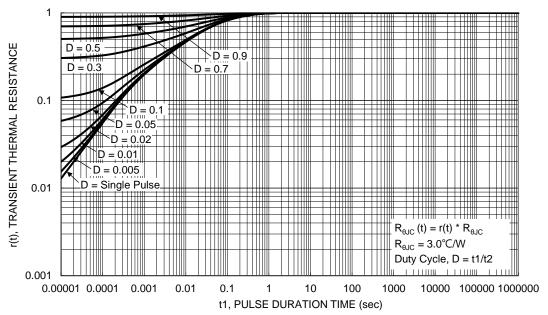


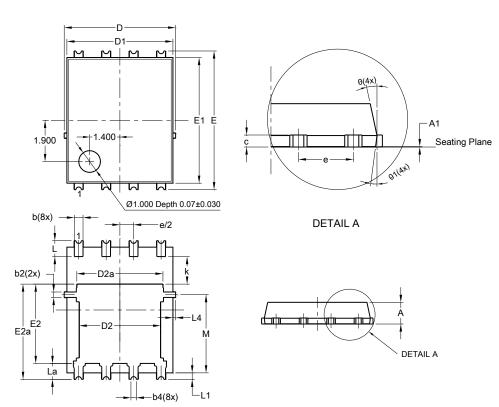
Figure 13. Transient Thermal Resistance



### **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI5060-8/SWP (Type UX)

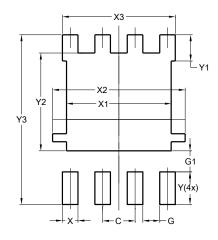


PowerDI5060-8/SWP						
(Type UX)						
Dim	Min	Max	Тур			
Α	0.90	1.10	1.00			
A1	0	0.05				
b	0.30	0.50	0.41			
b2	0.20	0.35	0.25			
b4	0.25REF					
С	0.230	0.330	0.277			
D	5	.15 BS0	)			
D1	4.70	5.10	4.90			
D2	3.56	3.96	3.76			
D2a	3.78	4.18	3.98			
E	6	.40 BS0	2			
E1	5.60	6.00	5.80			
E2	3.46	3.86	3.66			
E2a	4.195	4.595	4.395			
е	1.27BSC					
k	1.05					
L	0.635	0.835	0.735			
La	0.635	0.835	0.735			
L1	0.200	0.400	0.300			
L1a	0.050REF					
L4	0.025	0.225	0.125			
M	3.205	4.005	3.605			
θ	10°	12°	11°			
θ1	6°	8°	7°			
All Dimensions in mm						

### **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI5060-8/SWP (Type UX)



Dimensions	Value		
Dilliciisions	(in mm)		
С	1.270		
G	0.660		
G1	0.820		
X	0.610		
X1	4.100		
X2	5.190		
Х3	4.420		
Y	1.270		
Y1	1.020		
Y2	3.810		
Y3	6.610		



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